

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20170615006A Qualification of Additional Assembly Site for select Devices

Change Notification / Sample Request

Date: September 06, 2017 **To:** PREMIER FARNELL PCN

Dear Customer:

Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

20170615006A Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICEWL1837MODGIMOCT

CUSTOMER PART NUMBER

null

Technical details of this Product Change follow on the next page(s).

| PCN Number: 20170 | | 70615 | 615006A | | | P | CN Date: | Sept. 6, 2017 | | |
|-------------------------------------|-------------------------|---|-----------------------------------|--------------------------|---|---------------|---------------------------|---------------|--------------------------|------------------|
| Title | e: Qualification of Add | | | Addit | ditional Assembly site for select Devices | | | | | |
| Customer PCN Man | | Aanade | ar | Dont | Quality Consid | | | | | |
| Cont | | | PCN /V | nariage | <u>=1</u> | Dept: | Quality Service | .es | | |
| Proposed 1 st Ship Sate: | | Sept | Sept. 19, 2017 Estimated Sample A | | ated Sample A | vaila | vailability: Provided upo | | | |
| Chan | ige Ty | pe: | | • | | | | | | |
| | | mbly Site | | | Assembly Process | | | | Assembly Materials | |
| | Desig | jn . | | | ☐ Electrical Specification | | tion | | Mechanical Specification | |
| | Test | Site | | | Packing/ | Shipping/L | abeling | | Test Process | |
| | Wafe | r Bump Si | ite | | Wafer Bu | ımp Mater | ial | | Wafer Bump Process | |
| | Wafe | r Fab Site | | | Wafer Fa | b Material | S [| | Wafer Fab Process | |
| | | | | | Part num | ber chang | е | | | |
| | | | | | | PCN Det | ails | | | |
| Desc | riptio | n of Cha | nge: | | | | | | | |
| | | | | | | | that were not in | | | |
| | | | | | | | olded in the de | | | |
| | | | or thes | se nev | w devices w | ill be 90 d | ays from this no | tice f | for these n | ewly added |
| devic | es onl | <mark>У.</mark> | | | | | | | | |
| Tovo | a Inatu | manta ia | ممامم | ad +a | | ho avaliti | nation of DTI ac s | | lditional Aa | aamahlu aita fau |
| | | | | | | | ation of PTI as a | | | |
| | nbly s | | ow. i | nere | are no sign | ilicalit ulli | erences in device | es bu | ilit betweel | i tile two |
| assei | libly 5 | ites. | | | | | | | | |
| Reas | on fo | r Change | : | | | | | | | |
| Conti | nuity | of Supply | | | | | | | | |
| Antio | cipate | d impact | on Fi | t, Fo | rm, Functi | on, Quali | ty or Reliability | (pc | sitive / n | egative): |
| None | | | | | | | | | | |
| Antic | cipate | d impact | on M | ateri | al Declara | tion | | | | |
| No Impact to | | Material Declarations or Product Content reports are driven from | | | | | | | | |
| the Material | | production data and will be available following the production release. | | | | | | | | |
| Declaration | | Upon production release the revised reports can be obtained from the | | | | | | | | |
| | TI ECO website. | | | | | | | | | |
| Chan | iges t | o produc | t iden | tifica | ation resul | ting from | this PCN: | | | |
| | | | | | | | | | | |
| | | Assembly Site Assemb | | sembly Site Origin (22L) | | L) Assemb | bly Country Code (21 | | Asse | embly City |
| | Assemb | | | | JJN | | TWN | | NEW ⁻ | TAIDEL CITY |
| | Jor | Jin | | | | | | | | TAIPEI CITY |
| | | Jin | | | אונו PT2 | | TWN | | HSIN | CHU CITY |
| | Jor | Jin | | | | | TWN | | HSIN | |
| | Jor | Jin | | | | | TWN | | HSIN | |
| | Jor | Jin | | | | | TWN | | HSIN | |
| | Jor | Jin | | | | | TWN | | HSIN | |
| | Jor | Jin | | | | | TWN | | HSIN | |
| | Jor | Jin | | | | | TWN | | HSIN | |
| | Jor | Jin | | | | | TWN | | HSIN | |

Sample product shipping label (not actual product label)



OPT: ITEM:



(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

Topside Device marking (if included):

Assembly site code for JJN= T

Assembly site code for PT2 = C

5A (L)T0:1750

| Product Affected | | | |
|--------------------|-----------------|-----------------|-----------------|
| WL1801MODGBMOCR | WL1805MODGBMOCT | WL1831MODGBMOCT | WL1837MODGIMOC |
| WL1801MODGBMOCR-WI | WL1807MODGIMOCR | WL1835MODGBMOCR | WL1837MODGIMOCR |
| WL1801MODGBMOCT | WL1807MODGIMOCT | WL1835MODGBMOCT | WL1837MODGIMOCT |
| WL1805MODGBMOCR | WL1831MODGBMOCR | | |



TI Information Selective Disclosure

Qualification Report

WL1835 MODULE - 2nd Source Plan - Assy site PTI

This Qualification report qualifies WL1801MOD, WL1805MOD & WL1835MOD for PTI Assembly

Product Attributes

| Attributes | Qual Device: WL1835MODGBMOC | QBS Device: WL1837MODGIMOC | |
|----------------|--------------------------------|-------------------------------|--|
| Assembly Site | PTI | PTI | |
| Package Family | Module | Module | |

⁻ QBS: Qual By Similarity

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition | Duration | Qual Device: WL1835MODGBMOC | QBS Device: WL1837MODGIMOC |
|-------|--|-----------------------------|--------------------------------|-------------------------------|
| PC | Preconditioning Level 3 | MSL3, 260C reflow | 1/50/0 | 1/230/0 |
| TC | Temperature Cycle, -40/105 | 500cy | 1/45/0 | 1/45/0 |
| UHAST | Unbiased Temperature and Humidity, 85C/85%RH | 500hr | | 1/45/0 |
| LTSL | Low Temperature Storage Bake -40C | 500hr | | 1/45/0 |
| HTSL | High Temperature Bake 105C | 500hr | | 1/45/0 |
| VVF | Vibration Variance Frequency | 20 - 2000 - 20 Hz Log sweep | | 1/5/0 |
| CDM | ESD CDM | 500V | 1/3/0 | 1/3/0 |
| HBM | ESD HBM | 1000V | 1/3/0 | 1/3/0 |

Preconditioning was performed for Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

⁻ Qual Device is qualified at MSL LEVEL3-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--------------------------------|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |